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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/546,174

Application of: Chih-Chlen Liu, Ta-Shan Tseng, W. B.

Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun

Filed: April 11, 2000

Art Unit: 1711

Examiner: Sergent, Rabon A.

Attomey Docket No. UMC-96-279 CON

For: HIGH DENSITY PLASMA CHEMICAL VAPOR

DEPOSITION PROCESS

AMENDA FATE AND DESC

AMENDMENT AND RESPONSE PURSUANT TO FINAL OFFICE ACTION DATED AUGUST 25, 2005

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir.

In response to the final office communication mailed August 25, 2005, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 11 of this paper.

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